

OL-TDA1308AUK

Wafer level chip-size package; 8 bumps; 0.61 x 0.84 x 0.38 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	15-12-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.57	-	0.61	0.65	mm
E	package width	0.8	-	0.84	0.88	mm
A	seated height	0.49	-	[tbd]	[tbd]	mm
A ₂	package height	0.37	-	0.38	0.39	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

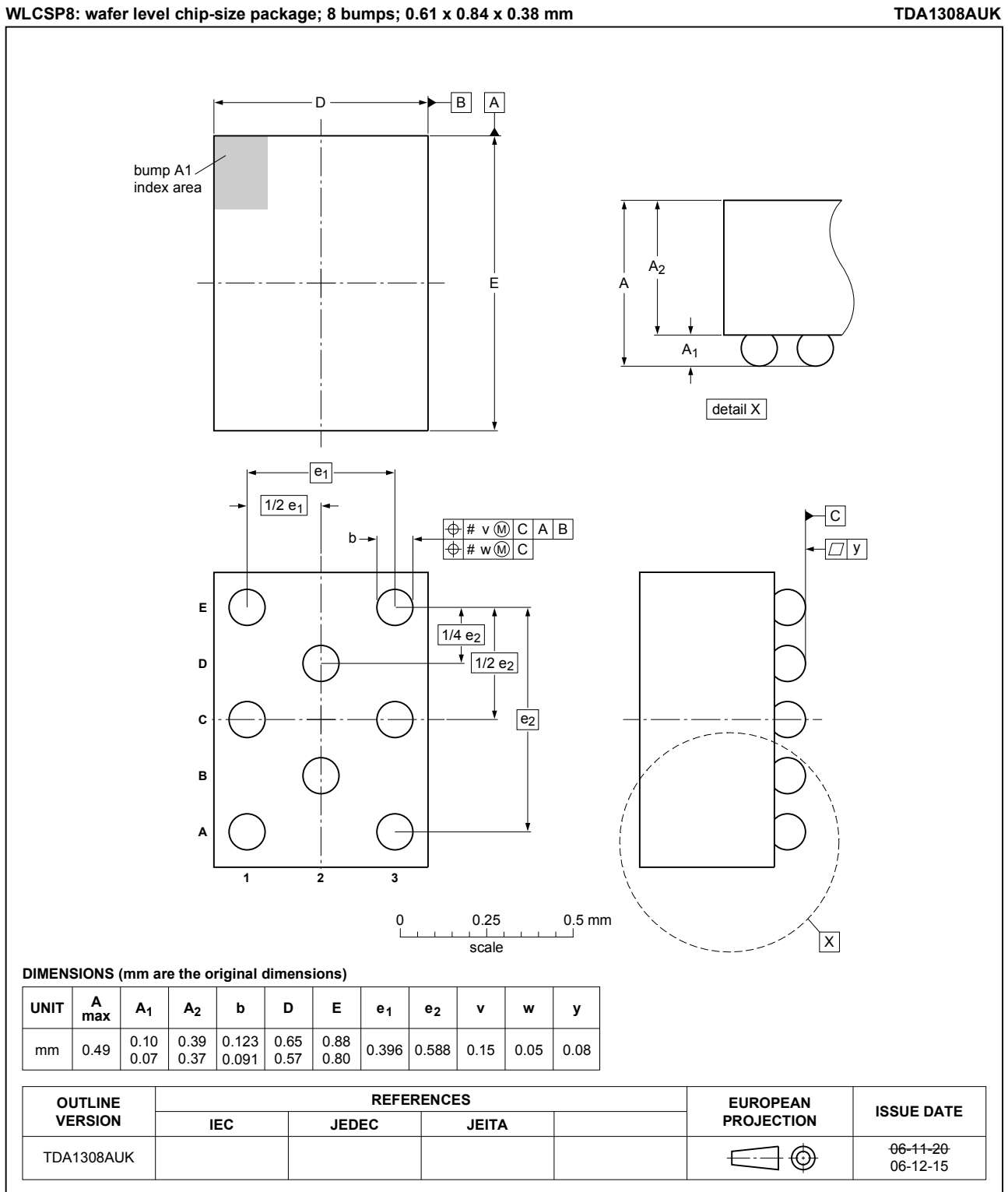


Fig. 1. Package outline WLCSP (OL-TDA1308AUK)

3. Legal information

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